PRESS RELEASE

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TechSearch International Projects Growth in FO-WLP Market

The fan-out wafer level package (FO-WLP) market is projected to grow 15.5% in units from 2020 to 2024. Growth is driven by use in mobile devices such as smartphones and smartwatches, automotive radar, and increasing adoption in high-performance computing. Wafer shipments are driven by adoption in AI accelerators, GPU/CPU, and networking applications with increasingly large areas. Foundry and OSAT players are introducing new versions. Alternatives are discussed, including silicon interposers, embedded bridge, and RDL interposers.

The new Advanced Packaging Update examines developments in integrated passives and the growing demand for high-performance substrates. A special section on integrated photonics is included, answering the question of “why now?” TechSearch International, Inc. details a number of factors that have come together to drive the adoption of integrated photonics, explaining that it is not a volume play, but rather a strategic move to support the sales of hardware and services.

TechSearch International’s new financial analysis of the OSAT market shows the importance of investments in advanced packaging. The latest APU is a 70-page report with full references and an accompanying set of 62 PowerPoint slides.

TechSearch International, Inc., founded in 1987, is a market research leader specializing in technology trends in microelectronics packaging and assembly. Multi- and single-client services encompass technology licensing, strategic planning, and market and technology analysis. TechSearch International professionals have an extensive network of more than 18,000 contacts in North America, Asia, and Europe. For more information, contact TechSearch at tel: 512-372-8887 or see www.techsearchinc.com. Follow us on twitter @Jan_TechSearch and on LinkedIn.